Serial Number: 10/820,291 Filing Date: April 8, 2004

Title: METHOD FOR FORMING A METALLIZATION LAYER

IN THE SPECIFICATION

Please amend the specification as follows:

The paragraph beginning at page 1, line 3 is amended as follows:

This application is a Divisional of U.S. Application No. 10/217,620, filed August 13, 2002, now U.S. Patent No. 6,753,254, which is a Divisional of U.S. Application No. 09/652,619, filed August 31, 2000, which is a Continuation of U.S. Application No. 08/912,051, filed August 18, 1997, now U.S. Patent No. 6,144,095, which is a Continuation of U.S. Application No. 08/656,712, filed June 3, 1996, now U.S. Patent No. 5,662,788.